

## **RB1** thermistors

S1	φ0.3 dumet wire	S3 Ø0.2 dumet wire
Configuration	Glass ohin	Configuration Glass Thermistor chip
Thermistor Baked electrode		Thermistor chip Baked electrode
Sanca creations	-1x0.5	



## High precision of ±1% tolerance in both resistance and B constant value

High precision both in resistance and B constant value has been achieved by reviewing the materials and manufacturing methods. While the maximum operating temperature is set lower than the standard

PSB thermistors, the RB1 keeps the basic structure of glass thermistors. Thus, it is more advantageous than general resin thermistors in resistance to soldering and thermal history through processes.

Features

- Chip with silver-palladium electrodes
- Saving cost by setting the upper temperature limit to 120°C
- Resistance and B constant specially designed within the tolerance of ±1%
- In High-level heat resistance and environmental stability secured by glass encapsulation
- Output is the second second

Applications For a variety of uses NOT under high temperatures

Operating<br/>temperature-50 to +120°CThermal time<br/>constantS1: Approx. 12 sec.S3: Approx. 5 sec.<br/>N: Approx. 12 sec.

## Reliability data

Heat resistance test (Capable of high temperature soldering and resin potting.)

rate	Sample: PX-42H	(average of $n = 10$ )
	at 300°C (assurance time: 20 min.)	
C drift	0	
sistan R25°	1	

Dissipation constant	S1: Approx. 1.3mW/°C S3: Approx. 0.75mW/°C	0		C	).5	1 h	
	N: Approx. 2.3mW/°C	Heat resistance test (The maximum operating temperature is 120°C.)					
		Sa 2	mple: PX-42	Н		(average of n = 10)	
Insulation	S1: Min. 50MQ at 500VDC	at at	20°C				
resistance	S3: Min. 10MΩ at 50VDC						
	N: Min. 100MΩ at 500VDC	Resistance drift rate (%) △ R25°C 1 0 1 5 -5 -1 -5 -1					
		ш ~	200	400 60	00 800	1000 1200 hrs	

